

IN THE SPECIFICATION

Kindly amend the specification as follows:

Page 15, lines 4-12:

In particular if the substrate 5 is a solid polystyrene layer and the final use of the composite involves a thermoforming step, typical thicknesses of the substrate will be from about 150 to about 2,000 $[\square\text{m}]$ μm , preferably from about 200 to about 1,500 $[\square\text{m}]$ μm , and more preferably from about 250 to about 1,000 $[\square\text{m}]$ μm ; if foam material is employed and the final use of the composite involves a thermoforming step, the substrate thickness is preferably comprised between about 1,000 and about 6,000 $[\square\text{m}]$ μm . Thicker layers however can be employed, if needed to get the required stiffness, provided that the end multilayer sheet can still be formed into a receptacle of the desired shape. If no thermoforming step is devised, thicker structures can be employed.